

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc6605cdjc-7#pbf

(Engineering Calculation)

DFN 6mm x 3mm Exp. Pad

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**TOTAL MASS (g) : 0.046731**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001291	1000000	27626.1699219		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.021187	975000	453381.59375		
		Iron (Fe)	7439-89-6	0.000522	24000	11170.3027344		
		Phosphorus (P)	7723-14-0	0.000007	300	149.793319702		
		Zinc (Zn)	7440-66-6	0.000015	700	320.985687256		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.021731</b>	<b>1000000</b>	<b>465022.6875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.001189	1000000	25444.6445312		
		<b>External Plating Total:</b>				<b>0.001189</b>	<b>1000000</b>	<b>25444.6445312</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000483	1000000	10335.7392578		
		<b>Internal Plating Total:</b>				<b>0.000483</b>	<b>1000000</b>	<b>10335.7392578</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000671	750000	14358.7597656		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000224	250000	4793.38623047		
<b>Die Attach Total:</b>				<b>0.000895</b>	<b>1000000</b>	<b>19152.1464844</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.002737	130000	58569.1835938		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.018107	860000	387472.53125		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000211	10000	4515.19921875		
		<b>Encapsulation Total:</b>				<b>0.021055</b>	<b>1000000</b>	<b>450556.90625</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000087	1000000	1861.71691895		
					<b>TOTAL MASS (g) :</b>	<b>0.046731</b>		